Silicon N Channel MOS FET High Speed Power Switching

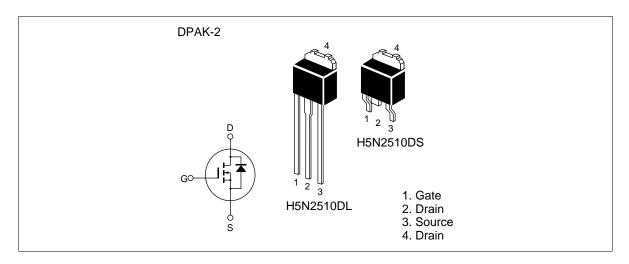
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ADE-208-1379 (Z) Target Specification 1st. Edition Mar. 2001

Features

- Low on-resistance
- Low drive current
- High speed switching

Outline





Absolute Maximum Ratings (Ta = 25° C)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	250	V	
Gate to source voltage	V _{GSS}	±20	V	
Drain current	I _D	(5)	A	
Drain peak current	Note1 D (pulse)	(20)	А	
Body-drain diode reverse drain current	I _{DR}	(5)	A	
Body-drain diode reverse drain peak current	Note1 DR (pulse)	(20)	A	
Channel dissipation	Pch Note2	25	W	
Channel to case Thermal Impedance	θ ch-c	5	°C/W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW 10 µs, duty cycle 1%

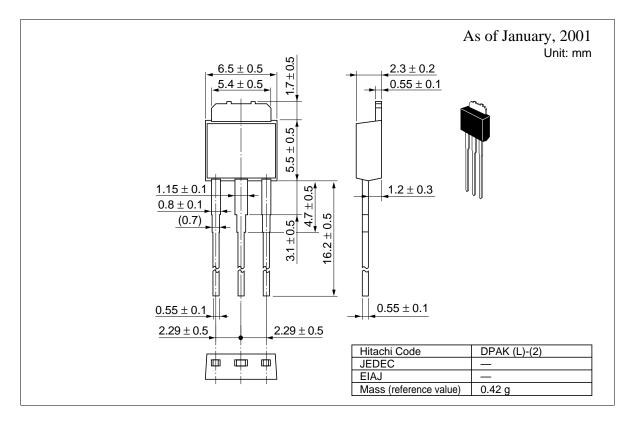
2. Value at Tc = 25°C

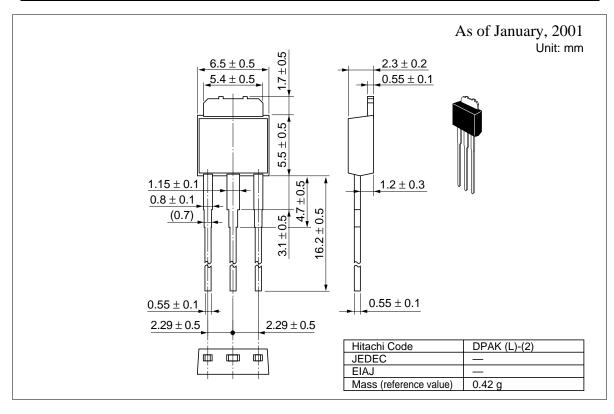
Electrical Characteristics (Ta = 25° C)

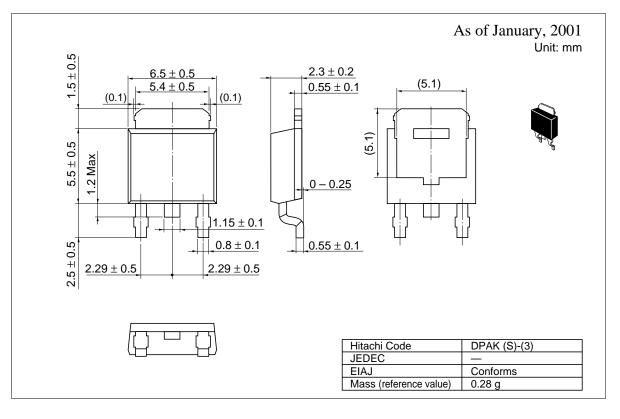
ltem	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	250	_	_	V	$I_{\rm D} = 10 \text{ mA}, V_{\rm GS} = 0$
Gate to source leak current	I _{GSS}	—	—	±0.1	μA	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	—	—	1	μA	$V_{\rm DS} = 250 \ V, \ V_{\rm GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	(1.0)	_	(2.5)	V	$V_{\rm DS} = 10 \text{ V}, \text{ I}_{\rm D} = 1 \text{ mA}$
Static drain to source on state	$R_{DS(on)}$	_	(0.68)	(0.89)		$I_{\rm D}$ = 2.5 A, $V_{\rm GS}$ = 10 V ^{Note4}
resistance	R _{DS(on)}	_	(0.72)	(0.97)		$I_{\rm D}$ = 2.5 A, $V_{\rm GS}$ = 10 V ^{Note4}
Forward transfer admittance	y _{fs}	(3.2)	(5.3)	_	S	$I_{\rm D} = 2.5 \text{ A}, V_{\rm DS} = 4 \text{ V}^{\text{Note4}}$
Input capacitance	Ciss	_	(390)	_	pF	V _{DS} = 25 V
Output capacitance	Coss	—	(45)	_	рF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	(13)		pF	f = 1 MHz
Total gate charge	Qg	—	(15.2)	_	nC	V _{DD} = 200 V
Gate to source charge	Qgs	—	(1.3)	_	nC	V _{GS} = 10 V
Gate to drain charge	Qgd	—	(5.1)	_	nC	I _D = 5 A
Turn-on delay time	td(on)	—	(12)	_	ns	I _D = 2.5 A
Rise time	tr	—	(14)	_	ns	V _{GS} = 10 V
Turn-off delay time	td(off)	_	(66)	—	ns	R _L = 50
Fall time	tf	—	(11)	_	ns	Rg = 10
Body-drain diode forward voltage	V_{DF}	—	(1.0)	(1.5)	V	$I_{F} = 5 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	trr		(100)	—	ns	$I_{F} = 5 A, V_{GS} = 0$
Body-drain diode reverse recovery charge	Qrr	—	(320)	—	nC	diF/dt = 100 A/µs

Note: 4. Pulse test

Package Dimensions







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